

Product Change Notification - JAON-26AJLN058

Date:

28 Feb 2020

Product Category:

Ethernet Switches

Affected CPNs:



Notification subject:

CCB 3867.001 Final Notice: Qualification of ASE as a new assembly site for selected Micrel KSZ8893 device family available in 100L LFBGA (9x9x1.38 mm) package.

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASE as a new assembly site for selected Micrel KSZ8893 device family available in 100L LFBGA (9x9x1.38 mm) package.

Pre Change:

Assembled at OSE assembly site using 2300 die attach and E770 molding compound.

Post Change:

Assembled at ASE assembly site using 2100A die attach and KE-G1250NAS molding compound.

Pre and Post Change Summary:

		Pre Change	Post Change			
Assembly Site		Orient Semiconductor	Advanced Semiconductor			
		Electronics, Ltd (OSE)	Engineering, Inc. (ASE)			
Wire material		Au	Au			
Die attach material		2300	2100A			
Molding compound material		E770	KE-G1250NAS			
	Core	HL832NX	HL832NX			
Substrate	Solder Mask	AUS308	AUS308			
material	Solder Mask Thickness	25 ± 10µm	30 ± 10µm			
Solder Ball		SAC305	SAC305			

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying ASE as a new assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:



April 17, 2020 (date code: 2016)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	February 2020			->	April 2020					
Workweek		7	8	9		14	15	16	17	18
Qual Report Availability				Χ						
Final PCN Issue Date				Χ						
Estimated Implementation Date								X		

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

February 28, 2020: Issued final notification. Attached the qualification report. Provided estimated first ship date to be on April 17, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_JAON-26AJLN058_Qual_Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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Date: Friday, February 28, 2020